

74LVC2G32

Dual 2-input OR gate

Rev. 13 — 3 July 2017

Product data sheet

1 General description

The 74LVC2G32 provides a 2-input OR gate function.

Inputs can be driven from either 3.3 V or 5 V devices. This feature allows the use of these devices as translators in a mixed 3.3 V and 5 V environment.

This device is fully specified for partial power-down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing a damaging backflow current through the device when it is powered down.

2 Features and benefits

- Wide supply voltage range from 1.65 V to 5.5 V
- 5 V tolerant outputs in the Power-down mode
- High noise immunity
- ± 24 mA output drive ($V_{CC} = 3.0$ V)
- CMOS low power consumption
- Complies with JEDEC standard:
 - JESD8-7 (1.65 V to 1.95 V)
 - JESD8-5 (2.3 V to 2.7 V)
 - JESD8-B/JESD36 (2.7 V to 3.6 V)
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Inputs accept voltages up to 5 V
- ESD protection:
 - HBM JESD22-A114F exceeds 2000 V
 - MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from -40 °C to $+85$ °C and -40 °C to $+125$ °C

3 Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LVC2G32DP	-40 °C to $+125$ °C	TSSOP8	plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm	SOT505-2
74LVC2G32DC	-40 °C to $+125$ °C	VSSOP8	plastic very thin shrink small outline package; 8 leads; body width 2.3 mm	SOT765-1

Type number	Package			
	Temperature range	Name	Description	Version
74LVC2G32GT	-40 °C to +125 °C	XSON8	plastic extremely thin small outline package; no leads; 8 terminals; body 1 x 1.95 x 0.5 mm	SOT833-1
74LVC2G32GF	-40 °C to +125 °C	XSON8	extremely thin small outline package; no leads; 8 terminals; body 1.35 x 1 x 0.5 mm	SOT1089
74LVC2G32GM	-40 °C to +125 °C	XQFN8	plastic, extremely thin quad flat package; no leads; 8 terminals; body 1.6 x 1.6 x 0.5 mm	SOT902-2
74LVC2G32GN	-40 °C to +125 °C	XSON8	extremely thin small outline package; no leads; 8 terminals; body 1.2 x 1.0 x 0.35 mm	SOT1116
74LVC2G32GS	-40 °C to +125 °C	XSON8	extremely thin small outline package; no leads; 8 terminals; body 1.35 x 1.0 x 0.35 mm	SOT1203
74LVC2G32GX	-40 °C to +125 °C	X2SON8	plastic thermal enhanced extremely thin small outline package; no leads; 8 terminals; body 1.35 x 0.8 x 0.35 mm	SOT1233

4 Marking

Table 2. Marking codes

Type number	Marking code ^[1]
74LVC2G32DP	V32
74LVC2G32DC	V32
74LVC2G32GT	V32
74LVC2G32GF	VG
74LVC2G32GM	V32
74LVC2G32GN	VG
74LVC2G32GS	VG
74LVC2G32GX	VG

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5 Functional diagram

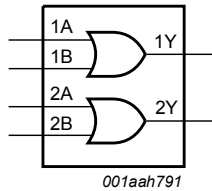


Figure 1. Logic symbol

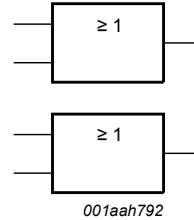


Figure 2. IEC logic symbol

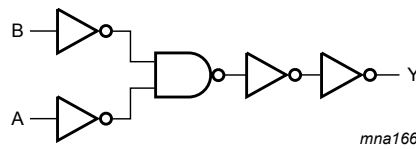


Figure 3. Logic diagram (one gate)

6 Pinning information

6.1 Pinning

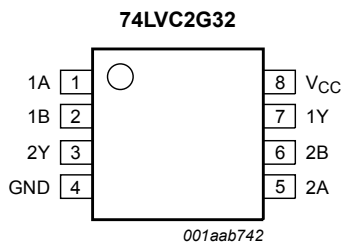


Figure 4. Pin configuration SOT505-2 and SOT765-1

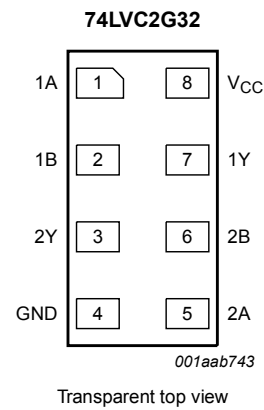


Figure 5. Pin configuration SOT833-1, SOT1089, SOT1116 and SOT1203

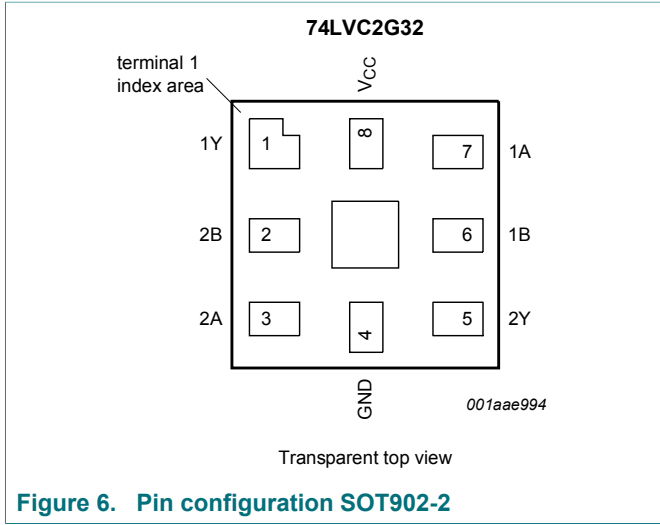


Figure 6. Pin configuration SOT902-2

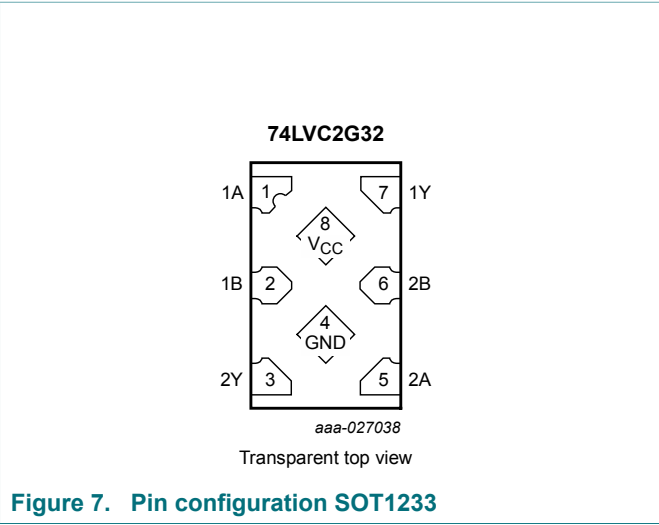


Figure 7. Pin configuration SOT1233

6.2 Pin description

Table 3. Pin description

Symbol	Pin		Description
	SOT505-2, SOT765-1, SOT833-1, SOT1089, SOT1116, SOT1203 and SOT1233	SOT902-2	
1A, 2A	1, 5	7, 3	data input
1B, 2B	2, 6	6, 2	data input
GND	4	4	ground (0 V)
1Y, 2Y	7, 3	1, 5	data output
V _{CC}	8	8	supply voltage

7 Functional description

Table 4. Function table

H = HIGH voltage level; L = LOW voltage level.

Input		Output
nA	nB	nY
L	L	L
L	H	H
H	L	H
H	H	H

8 Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+6.5	V
V_I	input voltage	[1]	-0.5	+6.5	V
V_O	output voltage	Active mode [1]	-0.5	$V_{CC} + 0.5$	V
		Power-down mode [2]	-0.5	+6.5	V
I_{IK}	input clamping current	$V_I < 0$ V	-50	-	mA
I_{OK}	output clamping current	$V_O < 0$ V or $V_O > V_{CC}$	-	± 50	mA
I_O	output current	$V_O = 0$ V to V_{CC}	-	± 50	mA
I_{CC}	supply current		-	100	mA
I_{GND}	ground current		-100	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +125 °C [3]	-	300	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] When $V_{CC} = 0$ V (Power-down mode), the output voltage can be 5.5 V in normal condition.

[3] For TSSOP8 package: above 55 °C the value of P_{tot} derates linearly with 2.5 mW/K.

For VSSOP8 package: above 110 °C the value of P_{tot} derates linearly with 8 mW/K.

For XSON8 and XQFN8 packages: above 118 °C the value of P_{tot} derates linearly with 7.8 mW/K.

For X2SON8 package: above 118 °C the value of P_{tot} derates linearly with 7.7 mW/K.

9 Recommended operating conditions

Table 6. Operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		1.65	5.5	V
V_I	input voltage		0	5.5	V
V_O	output voltage	Active mode	0	V_{CC}	V
		Power-down mode	0	5.5	V
T_{amb}	ambient temperature		-40	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 1.65$ V to 2.7 V	-	20	ns/V
		$V_{CC} = 2.7$ V to 5.5 V	-	10	ns/V

10 Static characteristics

Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
$T_{amb} = -40\text{ °C to }+85\text{ °C}$						
V_{IH}	HIGH-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	$0.65 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7	-	-	V
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	2.0	-	-	V
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	$0.7 \times V_{CC}$	-	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	-	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	-	-	0.7	V
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	-	-	0.8	V
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	-	-	$0.3 \times V_{CC}$	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}\text{ or }V_{IL}$				
		$I_O = -100\text{ }\mu\text{A}; V_{CC} = 1.65\text{ V to }5.5\text{ V}$	$V_{CC} - 0.1$	-	-	V
		$I_O = -4\text{ mA}; V_{CC} = 1.65\text{ V}$	1.2	1.53	-	V
		$I_O = -8\text{ mA}; V_{CC} = 2.3\text{ V}$	1.9	2.13	-	V
		$I_O = -12\text{ mA}; V_{CC} = 2.7\text{ V}$	2.2	2.50	-	V
		$I_O = -24\text{ mA}; V_{CC} = 3.0\text{ V}$	2.3	2.60	-	V
		$I_O = -32\text{ mA}; V_{CC} = 4.5\text{ V}$	3.8	4.10	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}\text{ or }V_{IL}$				
		$I_O = 100\text{ }\mu\text{A}; V_{CC} = 1.65\text{ V to }5.5\text{ V}$	-	-	0.1	V
		$I_O = 4\text{ mA}; V_{CC} = 1.65\text{ V}$	-	0.08	0.45	V
		$I_O = 8\text{ mA}; V_{CC} = 2.3\text{ V}$	-	0.14	0.3	V
		$I_O = 12\text{ mA}; V_{CC} = 2.7\text{ V}$	-	0.19	0.4	V
		$I_O = 24\text{ mA}; V_{CC} = 3.0\text{ V}$	-	0.37	0.55	V
		$I_O = 32\text{ mA}; V_{CC} = 4.5\text{ V}$	-	0.43	0.55	V
I_I	input leakage current	$V_I = 5.5\text{ V or GND}; V_{CC} = 0\text{ V to }5.5\text{ V}$	-	± 0.1	± 1	μA
I_{OFF}	power-off leakage current	$V_I\text{ or }V_O = 5.5\text{ V}; V_{CC} = 0\text{ V}$	-	± 0.1	± 2	μA
I_{CC}	supply current	$V_I = 5.5\text{ V or GND};$ $V_{CC} = 1.65\text{ V to }5.5\text{ V}; I_O = 0\text{ A}$	-	0.1	4	μA
ΔI_{CC}	additional supply current	per pin; $V_I = V_{CC} - 0.6\text{ V};$ $V_{CC} = 2.3\text{ V to }5.5\text{ V}; I_O = 0\text{ A}$	-	5	500	μA
C_i	input capacitance		-	2.5	-	pF

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
$T_{amb} = -40\text{ °C to }+125\text{ °C}$						
V_{IH}	HIGH-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	$0.65 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7	-	-	V
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	2.0	-	-	V
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	$0.7 \times V_{CC}$	-	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	-	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	-	-	0.7	V
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	-	-	0.8	V
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	-	-	$0.3 \times V_{CC}$	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}\text{ or }V_{IL}$				
		$I_O = -100\text{ }\mu\text{A}; V_{CC} = 1.65\text{ V to }5.5\text{ V}$	$V_{CC} - 0.1$	-	-	V
		$I_O = -4\text{ mA}; V_{CC} = 1.65\text{ V}$	0.95	-	-	V
		$I_O = -8\text{ mA}; V_{CC} = 2.3\text{ V}$	1.7	-	-	V
		$I_O = -12\text{ mA}; V_{CC} = 2.7\text{ V}$	1.9	-	-	V
		$I_O = -24\text{ mA}; V_{CC} = 3.0\text{ V}$	2.0	-	-	V
		$I_O = -32\text{ mA}; V_{CC} = 4.5\text{ V}$	3.4	-	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}\text{ or }V_{IL}$				
		$I_O = 100\text{ }\mu\text{A}; V_{CC} = 1.65\text{ V to }5.5\text{ V}$	-	-	0.1	V
		$I_O = 4\text{ mA}; V_{CC} = 1.65\text{ V}$	-	-	0.70	V
		$I_O = 8\text{ mA}; V_{CC} = 2.3\text{ V}$	-	-	0.45	V
		$I_O = 12\text{ mA}; V_{CC} = 2.7\text{ V}$	-	-	0.60	V
		$I_O = 24\text{ mA}; V_{CC} = 3.0\text{ V}$	-	-	0.80	V
		$I_O = 32\text{ mA}; V_{CC} = 4.5\text{ V}$	-	-	0.80	V
I_I	input leakage current	$V_I = 5.5\text{ V or GND}; V_{CC} = 0\text{ V to }5.5\text{ V}$	-	-	± 1	μA
I_{OFF}	power-off leakage current	$V_I\text{ or }V_O = 5.5\text{ V}; V_{CC} = 0\text{ V}$	-	-	± 2	μA
I_{CC}	supply current	$V_I = 5.5\text{ V or GND};$ $V_{CC} = 1.65\text{ V to }5.5\text{ V}; I_O = 0\text{ A}$	-	-	4	μA
ΔI_{CC}	additional supply current	per pin; $V_I = V_{CC} - 0.6\text{ V};$ $V_{CC} = 2.3\text{ V to }5.5\text{ V}; I_O = 0\text{ A}$	-	-	500	μA

[1] All typical values are measured at $T_{amb} = 25\text{ °C}$.

11 Dynamic characteristics

Table 8. Dynamic characteristics

Voltages are referenced to GND (ground 0 V); for test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
t _{pd}	propagation delay	nA, nB to nY; see Figure 8 ^[2]						
		V _{CC} = 1.65 V to 1.95 V	1.3	3.9	8.8	1.3	11	ns
		V _{CC} = 2.3 V to 2.7 V	0.8	2.4	4.7	0.8	5.9	ns
		V _{CC} = 2.7 V	0.8	2.7	4.8	0.8	6.0	ns
		V _{CC} = 3.0 V to 3.6 V	0.9	2.2	4.2	0.9	5.3	ns
		V _{CC} = 4.5 V to 5.5 V	0.7	1.7	3.2	0.7	4.0	ns
C _{PD}	power dissipation capacitance	per gate; V _I = GND to V _{CC} ^[3]	-	14	-	-	-	pF

[1] Typical values are measured at nominal V_{CC} and at T_{amb} = 25 °C.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

∑(C_L × V_{CC}² × f_o) = sum of outputs.

11.1 Waveforms and test circuit

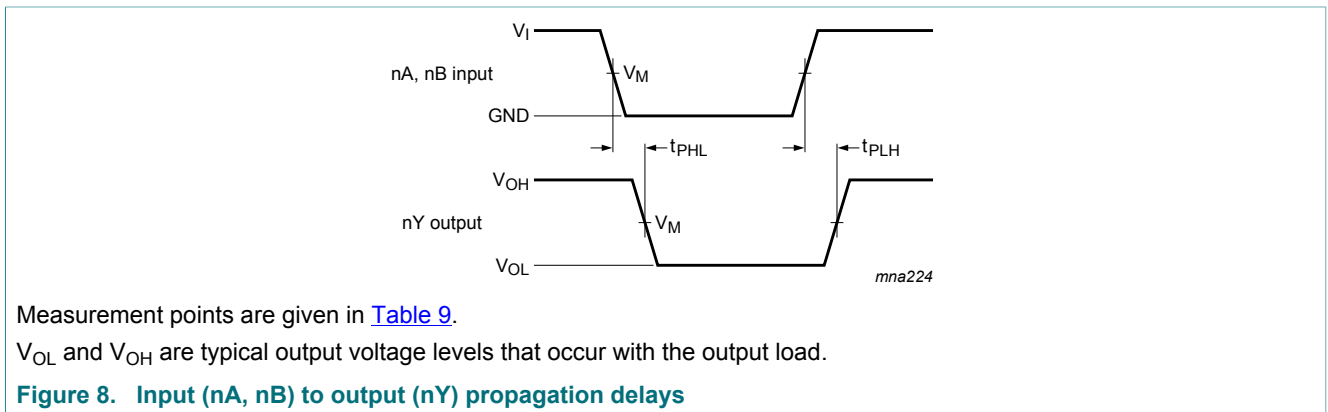
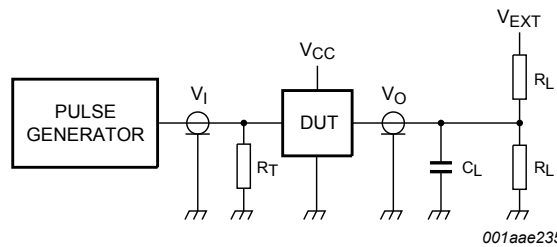
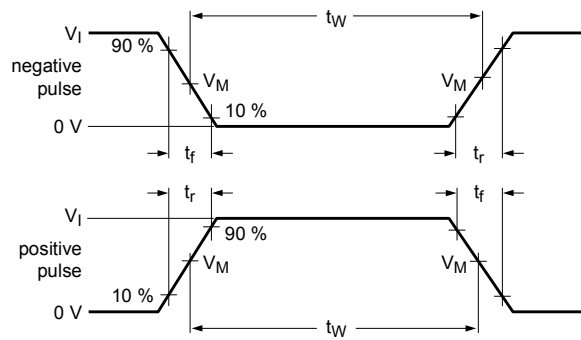


Table 9. Measurement points

Supply voltage	Input	Output
V_{CC}	V_M	V_M
1.65 V to 1.95 V	$0.5V_{CC}$	$0.5V_{CC}$
2.3 V to 2.7 V	$0.5V_{CC}$	$0.5V_{CC}$
2.7 V	1.5 V	1.5 V
3.0 V to 3.6 V	1.5 V	1.5 V
4.5 V to 5.5 V	$0.5V_{CC}$	$0.5V_{CC}$



Test data is given in [Table 10](#).

Definitions for test circuit:

R_L = Load resistance

C_L = Load capacitance including jig and probe capacitance

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator

V_{EXT} = Test voltage for switching times

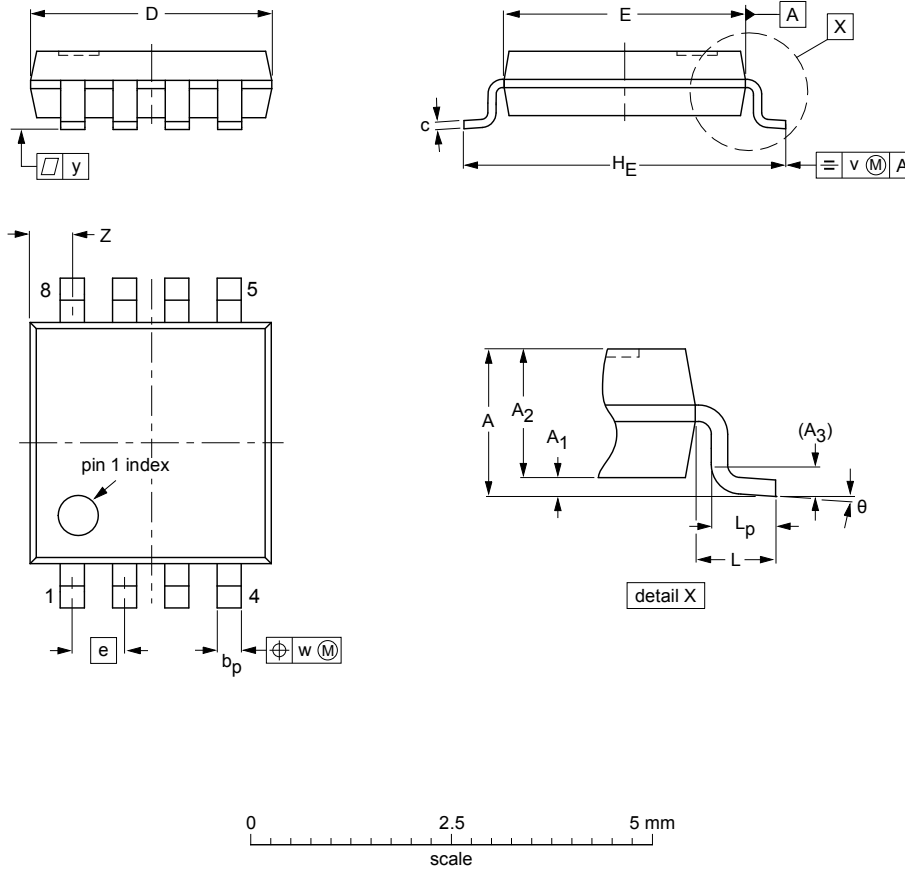
Figure 9. Test circuit for measuring switching times

Table 10. Test data

Supply voltage	Input	Load	V_{EXT}	
V_{CC}	V_I	t_r, t_f	C_L , R_L	
			t_{PLH}, t_{PHL}	
1.65 V to 1.95 V	V_{CC}	≤ 2.0 ns	30 pF, 1 k Ω	open
2.3 V to 2.7 V	V_{CC}	≤ 2.0 ns	30 pF, 500 Ω	open
2.7 V	2.7 V	≤ 2.5 ns	50 pF, 500 Ω	open
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF, 500 Ω	open
4.5 V to 5.5 V	V_{CC}	≤ 2.5 ns	50 pF, 500 Ω	open

12 Package outline

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm SOT505-2



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	v	w	y	Z ⁽¹⁾	θ
mm	1.1	0.15 0.00	0.95 0.75	0.25	0.38 0.22	0.18 0.08	3.1 2.9	3.1 2.9	0.65	4.1 3.9	0.5	0.47 0.33	0.2	0.13	0.1	0.70 0.35	8° 0°

Note

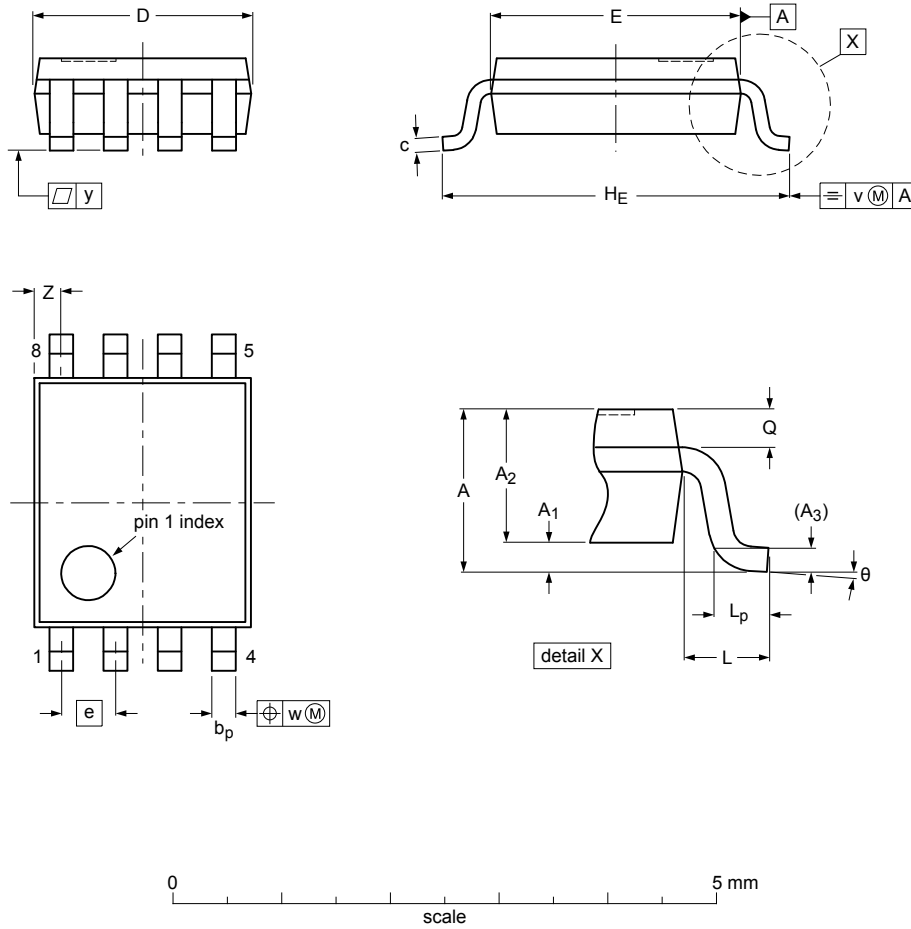
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT505-2		---			02-01-16

Figure 10. Package outline SOT505-2 (TSSOP8)

VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

SOT765-1



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
	max.																	
mm	max	0.15	0.85		0.27	0.23	2.1	2.4		3.2		0.40	0.21				0.4	8°
	nom	1		0.12					0.5		0.4			0.2	0.08	0.1		
	min		0.00	0.60		0.17	0.08	1.9	2.2	3.0		0.15	0.19				0.1	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

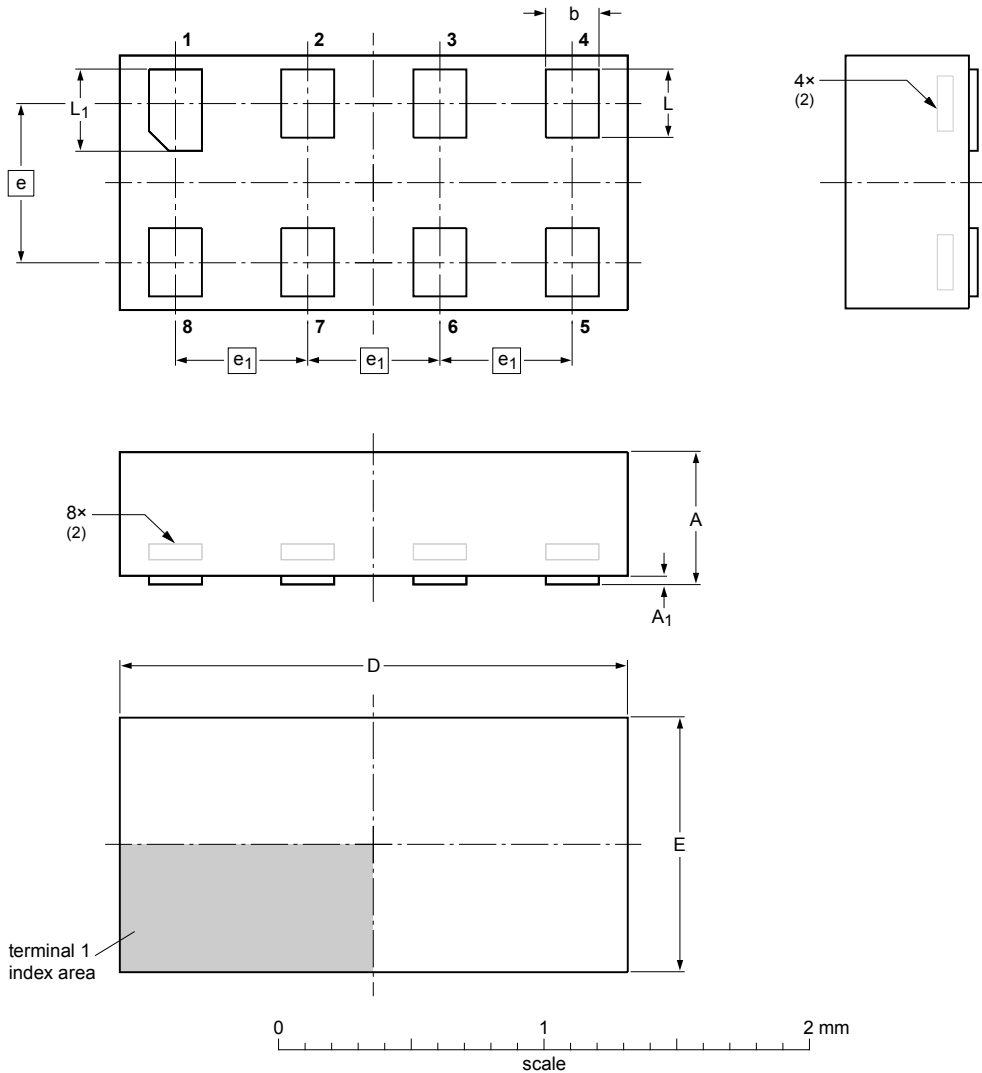
sot765-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT765-1		MO-187				07-06-02 16-05-31

Figure 11. Package outline SOT765-1 (VSSOP8)

XSON8: plastic extremely thin small outline package; no leads; 8 terminals; body 1 x 1.95 x 0.5 mm

SOT833-1



DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max	A ₁ max	b	D	E	e	e ₁	L	L ₁
mm	0.5	0.04	0.25 0.17	2.0 1.9	1.05 0.95	0.6	0.5	0.35 0.27	0.40 0.32

Notes

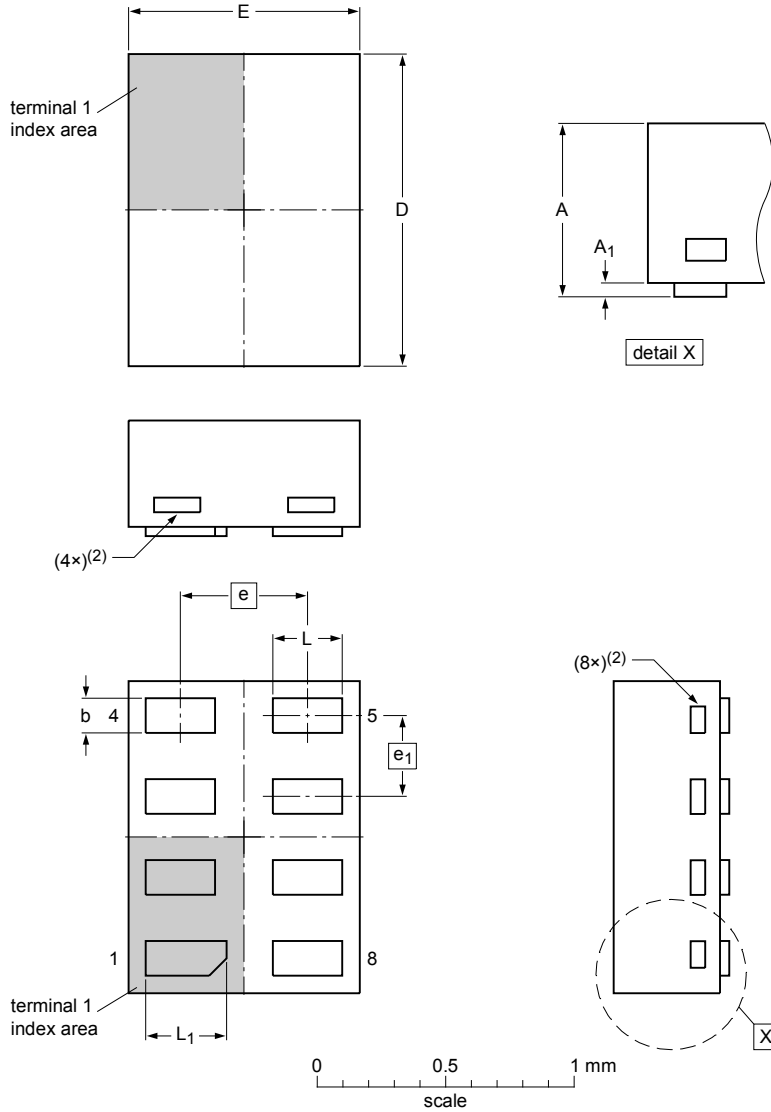
- Including plating thickness.
- Can be visible in some manufacturing processes.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT833-1	---	MO-252	---		07-11-14 07-12-07

Figure 12. Package outline SOT833-1 (XSON8)

**XSON8: extremely thin small outline package; no leads;
8 terminals; body 1.35 x 1 x 0.5 mm**

SOT1089



Dimensions

Unit	A ⁽¹⁾	A ₁	b	D	E	e	e ₁	L	L ₁
max	0.5	0.04	0.20	1.40	1.05			0.35	0.40
nom			0.15	1.35	1.00	0.55	0.35	0.30	0.35
min			0.12	1.30	0.95			0.27	0.32

Note

- Including plating thickness.
- Visible depending upon used manufacturing technology.

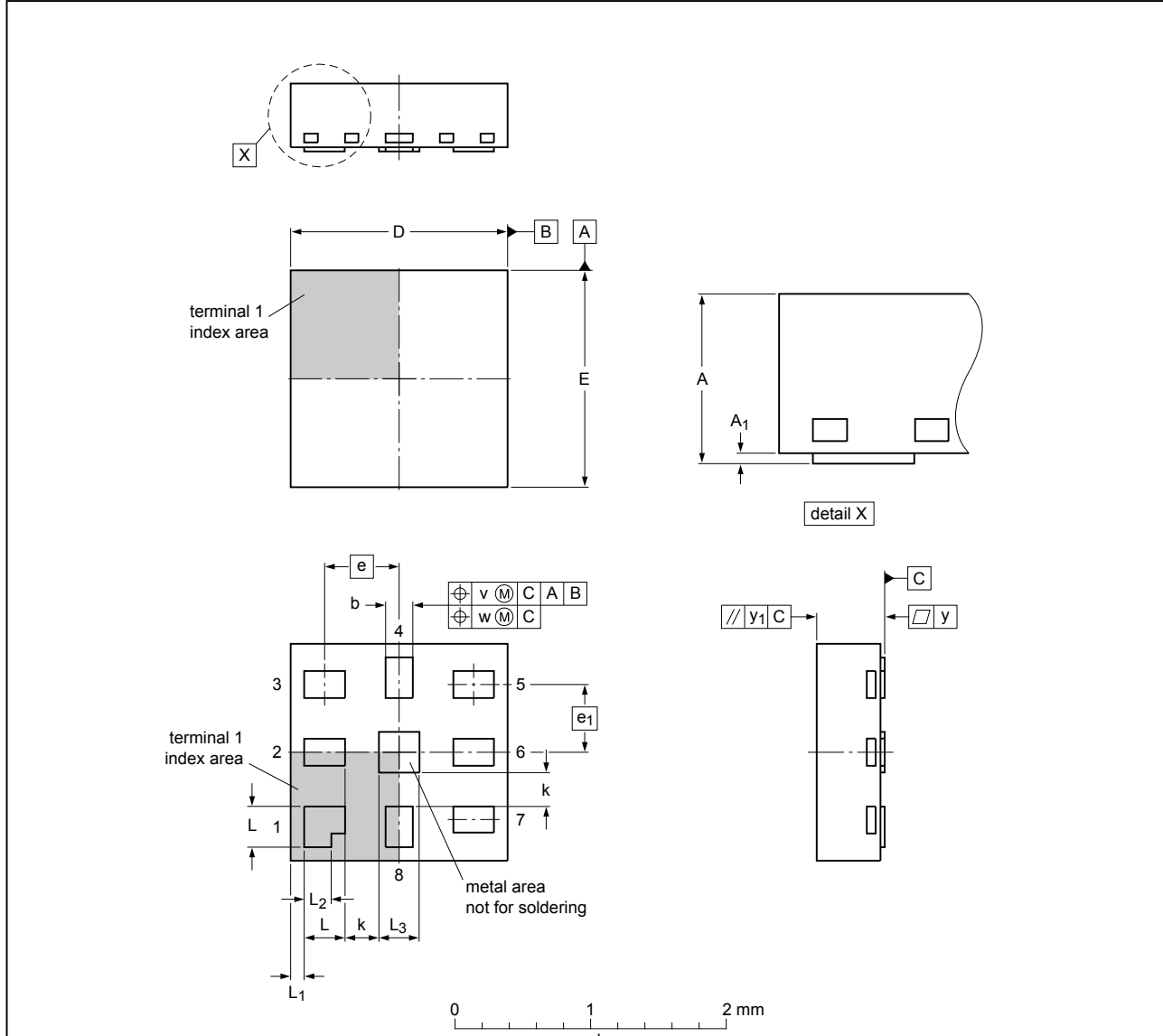
sot1089_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1089		MO-252				10-04-09 10-04-12

Figure 13. Package outline SOT1089 (XSON8)

**XQFN8: plastic, extremely thin quad flat package; no leads;
8 terminals; body 1.6 x 1.6 x 0.5 mm**

SOT902-2



Dimensions

Unit ⁽¹⁾	A	A ₁	b	D	E	e	e ₁	k	L	L ₁	L ₂	L ₃	v	w	y	y ₁
max	0.5	0.05	0.25	1.65	1.65				0.35	0.15	0.25	0.35				
mm	nom		0.20	1.60	1.60	0.55	0.5		0.30	0.10	0.20	0.30	0.1	0.05	0.05	0.05
	min	0.00	0.15	1.55	1.55			0.2	0.25	0.05	0.15	0.25				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

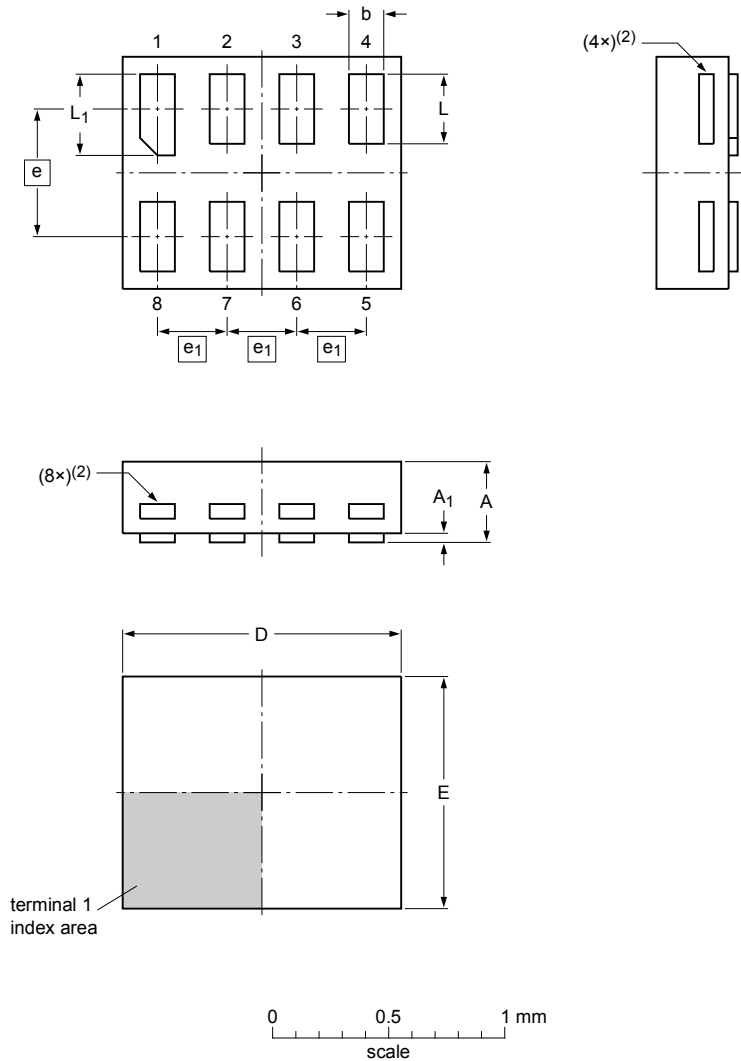
sot902-2_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT902-2	---	MO-255	---			16-07-14 16-11-08

Figure 14. Package outline SOT902-2 (XQFN8)

XSON8: extremely thin small outline package; no leads;
8 terminals; body 1.2 x 1.0 x 0.35 mm

SOT1116



Dimensions

Unit	A ⁽¹⁾	A ₁	b	D	E	e	e ₁	L	L ₁
max	0.35	0.04	0.20	1.25	1.05			0.35	0.40
nom			0.15	1.20	1.00	0.55	0.3	0.30	0.35
min			0.12	1.15	0.95			0.27	0.32

Note

- Including plating thickness.
- Visible depending upon used manufacturing technology.

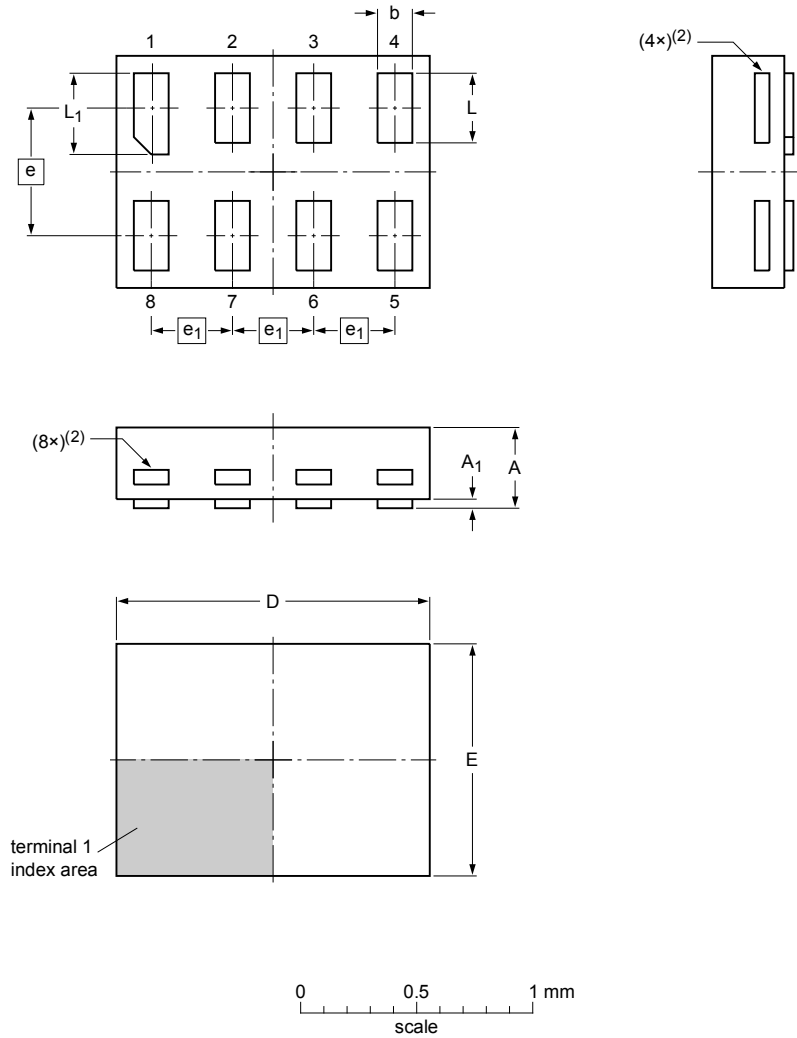
sot1116_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1116						-10-04-02- 10-04-07

Figure 15. Package outline SOT1116 (XSON8)

XSON8: extremely thin small outline package; no leads;
8 terminals; body 1.35 x 1.0 x 0.35 mm

SOT1203



Dimensions

Unit	A ⁽¹⁾	A ₁	b	D	E	e	e ₁	L	L ₁
mm	max 0.35	0.04	0.20	1.40	1.05			0.35	0.40
	nom		0.15	1.35	1.00	0.55	0.35	0.30	0.35
	min		0.12	1.30	0.95			0.27	0.32

Note

- Including plating thickness.
- Visible depending upon used manufacturing technology.

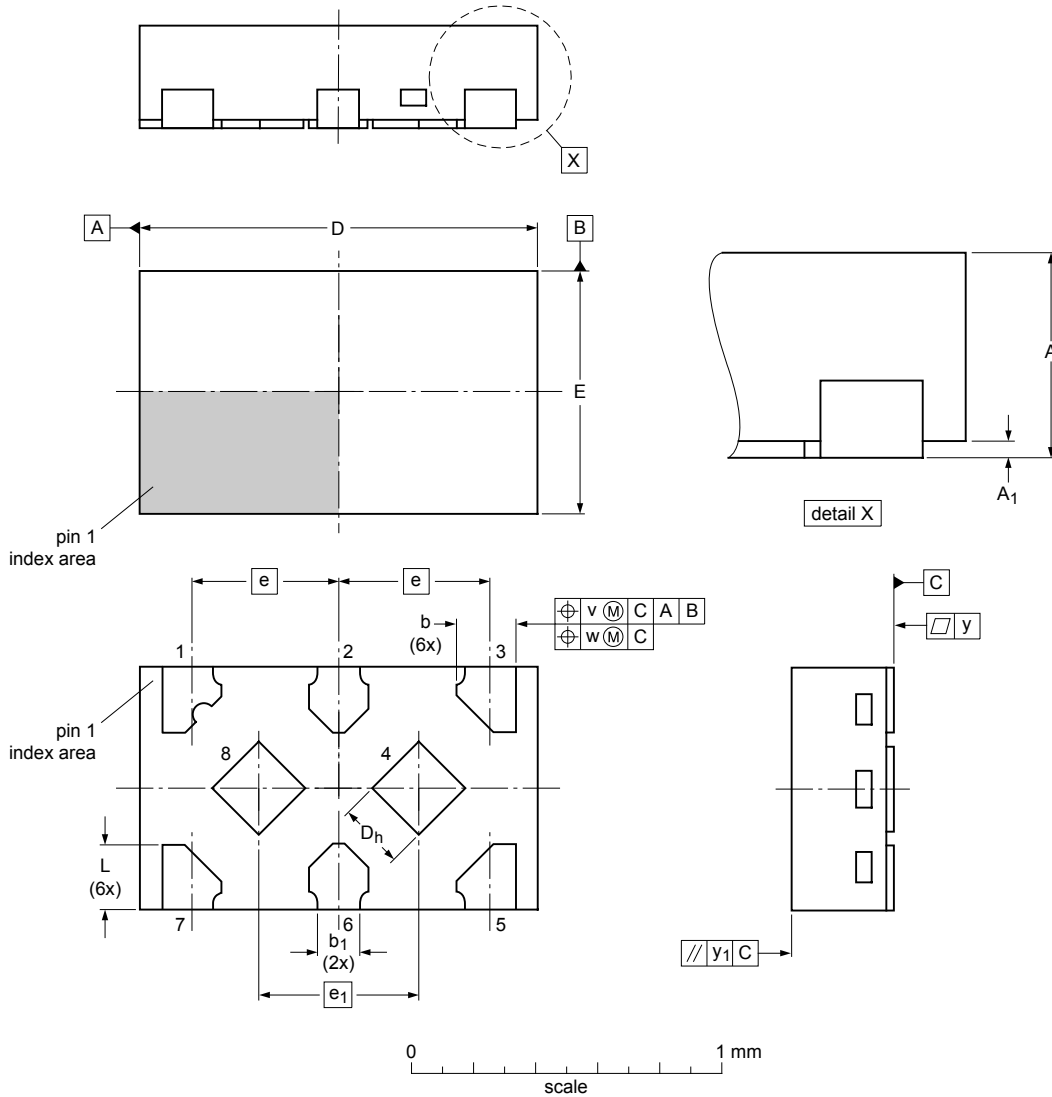
sot1203_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1203						-10-04-02- 10-04-06

Figure 16. Package outline SOT1203 (XSON8)

X2SON8: plastic thermal enhanced extremely thin small outline package; no leads;
8 terminals; body 1.35 x 0.8 x 0.35 mm

SOT1233



Dimensions (mm are the original dimensions)

Unit	A	A ₁	b	b ₁	D	D _h	E	e	e ₁	L	v	w	y	y ₁
max	0.35	0.04	0.25		1.40	0.27	0.85			0.27				
nom	0.32		0.20	0.15	1.35	0.22	0.80	0.5	0.54	0.22	0.1	0.05	0.05	0.05
min	0.30	0.00	0.15	(ref)	1.30	0.17	0.75			0.17				

sot1233_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1233		---				16-04-21 17-01-05

Figure 17. Package outline SOT1233 (X2SON8)

13 Abbreviations

Table 11. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14 Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC2G32v.13	20170703	Product data sheet	-	74LVC2G32v.12
Modifications:	<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia. Legal texts have been adapted to the new company name where appropriate. Type number 74LVC2G32GX (SOT1233 / X2SON8) added. Type number 74LVC2G32GD removed. 			
74LVC2G32v.12	20161215	Product data sheet	-	74LVC2G32v.11
Modifications:	<ul style="list-style-type: none"> Table 7: The maximum limits for leakage current and supply current have changed. 			
74LVC2G32v.11	20130408	Product data sheet	-	74LVC2G32 v.10
Modifications:	<ul style="list-style-type: none"> For type number 74LVC2G32GD XSON8U has changed to XSON8. 			
74LVC2G32 v.10	20120622	Product data sheet	-	74LVC2G32 v.9
Modifications:	<ul style="list-style-type: none"> For type number 74LVC2G32GM the SOT code has changed to SOT902-2. 			
74LVC2G32 v.9	20111128	Product data sheet	-	74LVC2G32 v.8
Modifications:	<ul style="list-style-type: none"> Legal pages updated. 			
74LVC2G32 v.8	20101110	Product data sheet	-	74LVC2G32 v.7
74LVC2G32 v.7	20080606	Product data sheet	-	74LVC2G32 v.6
74LVC2G32 v.6	20080227	Product data sheet	-	74LVC2G32 v.5
74LVC2G32 v.5	20070904	Product data sheet	-	74LVC2G32 v.4
74LVC2G32 v.4	20060515	Product data sheet	-	74LVC2G32 v.3
74LVC2G32 v.3	20050201	Product specification	-	74LVC2G32 v.2
74LVC2G32 v.2	20040922	Product specification	-	74LVC2G32 v.1
74LVC2G32 v.1	20031027	Product specification	-	-

15 Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nexperia.com>.

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Contents

1	General description	1
2	Features and benefits	1
3	Ordering information	1
4	Marking	2
5	Functional diagram	3
6	Pinning information	3
6.1	Pinning	3
6.2	Pin description	4
7	Functional description	4
8	Limiting values	5
9	Recommended operating conditions	5
10	Static characteristics	6
11	Dynamic characteristics	8
11.1	Waveforms and test circuit	8
12	Package outline	10
13	Abbreviations	18
14	Revision history	18
15	Legal information	19

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Date of release: 3 July 2017

Document identifier: 74LVC2G32

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